- Phase-Locked Loop-Based Zero-Delay Buffer
- Operating Frequency: 8 MHz to 200 MHz
- Low Jitter (Cycle-Cycle): ±100 ps Over the Range 66 MHz to 200 MHz
- Distributes One Clock Input to Two Banks of Four Outputs
- Auto Frequency Detection to Disable Device (Power Down Mode)
- Consumes Less Than 20 μA in Power Down Mode
- Operates From Single 3.3-V Supply
- Industrial Temperature Range –40°C to 85°C
- 25-Ω On-Chip Series Damping Resistors
- No External RC Network Required
- Spread Spectrum Clock Compatible (SSC)
- Available in 16-Pin TSSOP or 16-Pin SOIC Packages

D PACKAGE (SOIC) PW PACKAGE (TSSOP) (TOP VIEW)

CLKIN \Box	10	16	☐ FBIN
1Y0 🗀	2	15	1Y3
1Y1 🗀	3	14	1Y2
V _{DD} \square	4	13	\square \lor_{DD}
GND □□	5	12	
2Y0 🗀	6	11	□□ 2Y3
2Y1 🗀	7	10	2Y2
S2 🗀	8	9	S1

description

The CDCVF25081 is a high-performance, low-skew, low-jitter, phase-lock loop clock driver. It uses a PLL to precisely align, in both frequency and phase, the output clocks to the input clock signal. The CDCVF25081 operates from a nominal supply voltage of 3.3 V. The device also includes integrated series-damping resistors in the output drivers that make it ideal for driving point-to-point loads.

Two banks of four outputs each provide low-skew, low-jitter copies of CLKIN. All outputs operate at the same frequency. Output duty cycles are adjusted to 50%, independent of duty cycle at CLKIN. The device automatically goes into power-down mode when no input signal is applied to CLKIN and the outputs go into a low state. Unlike many products containing PLLs, the CDCVF25081 does not require an external RC network. The loop filter for the PLL is included on-chip, minimizing component count, space, and cost.

Because it is based on a PLL circuitry, the CDCVF25081 requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization is required following power up and application of a fixed-frequency signal at CLKIN and any following changes to the PLL reference.

The CDCVF25081 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

S2	S1	1Y0-1Y3	2Y0-2Y3	OUTPUT SOURCE	PLL SHUTDOWN
0	0	Hi-Z	Hi-Z	N/A.	Yes
0	1	Active	Hi-Z	PLL [†]	No
1	0	Active	Active	Input clock (PLL bypass)	Yes
1	1	Active	Active	PLL [†]	No

† CLK input frequency < 2 MHz switches the outputs to low level



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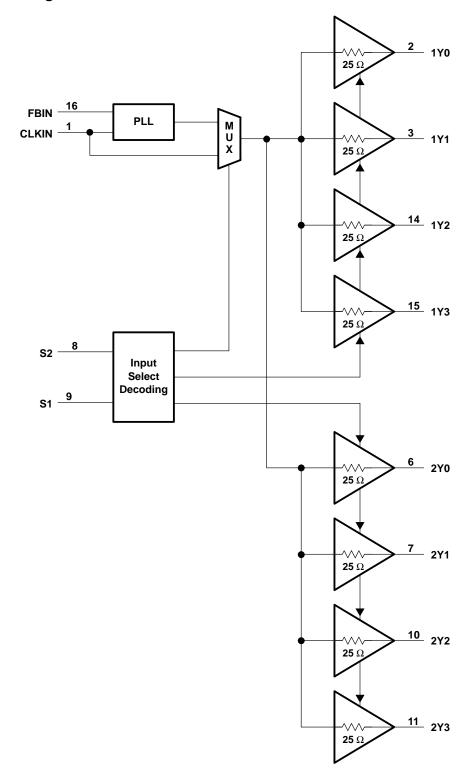


Terminal Functions

TERMINAL			DESCRIPTION.				
NAME	PIN NO.	TYPE	DESCRIPTION				
1Y[0:3]	2, 3, 14, 15	0	Bank 1Yn clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated $25-\Omega$ series-damping resistor.				
2Y[0:3]	6, 7, 10, 11	0	Bank 2Yn clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated $25-\Omega$ series-damping resistor.				
CLKIN	1	I	Clock input. CLKIN provides the clock signal to be distributed by the CDCVF25081 clock driver. CLKIN is used to provide the reference signal to the integrated PLL that generates the output signal. CLKIN must have a fixed frequency and phase in order for the PLL to acquire lock. Once the circuit is powered up and a valid signal is applied, a stabilization time is required for the PLL to phase lock the feedback signal to CLKIN.				
FBIN	16	_	Feedback input. FBIN provides the feedback signal to the internal PLL. FBIN must be wired to one of the outputs to complete the feedback loop of the internal PLL. The integrated PLL synchronizes the FBIN and output signal so there is nominally zero-delay from input clock to output clock.				
GND	5, 12	Ground	Ground				
S1, S2	9, 8	I	Select pins to determine mode of operation. See the FUNCTION TABLE for mode selection options.				
V_{DD}	4, 13	Power	Supply voltage. The supply voltage range is 3 V to 3.6 V				



functional block diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V _{DD}	–0.5 V to 4.6 V
Input voltage range, V _I (see Notes 1 and 2)	0.5 V to 4.6 V
Output voltage range, V _O (see Notes 1 and 2)	\dots -0.5 V to V _{DD} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I_{OK} ($V_O < 0$)	
Continuous total output current, $I_O(V_O = 0 \text{ to } V_{DD})$	
Package thermal impedance, θ _{IA} (see Note 3): PW package	
D package	112°C/W
Storage temperature range, T _{sto}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	3	3.3	3.6	V
Low level input voltage, V _{IL}			8.0	V
High level input voltage, V _{IH}	2			V
Input voltage, V _I	0		3.6	V
High-level output current, IOH			-12	mA
Low-level output current, I _{OL}			12	mA
Operating free-air temperature, T _A	-40		85	°C

timing requirements over recommended ranges of supply voltage, load and operating free-air temperature

		MIN	NOM	MAX	UNIT
Clock frequency, f _{Clk}	$C_L = 25 pF$	8		100	NAL 1-
	C _L = 15 pF	66		200	MHz



NOTES: 1. The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CO	TEST CONDITIONS		TYP [†]	MAX	UNIT
VIK	Input voltage	$V_{DD} = 3 V$,	I _I = -18 mA			-1.2	V
II	Input current	$V_I = 0 \text{ V or } V_{DD}$				±5	μΑ
I _{PD} ‡	Power down current	f _{CLKIN} = 0 MHz,	V _{DD} = 3.3 V			20	μΑ
loz	Output 3-state	$V_0 = 0 \text{ V or } V_{DD}$	V _{DD} = 3.6 V			±5	μΑ
Cl	Input capacitance at FBIN, CLKIN	$V_I = 0 V \text{ or } V_{DD}$			4		pF
Cl	Input capacitance at S1, S2	$V_I = 0 V \text{ or } V_{DD}$			2.2		pF
CO	Output capacitance	$V_I = 0 V \text{ or } V_{DD}$			3		pF
		$V_{DD} = min to max,$	I _{OH} = -100 μA	V _{DD} – 0.2			
∨он	High-level output voltage	$V_{DD} = 3 V$,	I _{OH} = -12 mA	2.1			V
		$V_{DD} = 3 V$,	I _{OH} = -6 mA	2.4			
		$V_{DD} = min to max,$	I _{OL} = 100 μA			0.2	
VOL	Low-level output voltage	$V_{DD} = 3 V$,	I _{OL} = 12 mA			8.0	V
		$V_{DD} = 3 V$,	$I_{OL} = 6 \text{ mA}$			0.55	
		$V_{DD} = 3 V$,	V _O = 1 V	-24			
lOH	High-level output current	$V_{DD} = 3.3 V$,	V _O = 1.65 V		-30		mA
		$V_{DD} = 3.6 V,$	V _O = 3.135 V			-15	
		$V_{DD} = 3 V$,	V _O = 1.95 V	26			
lOL	Low-level output current	$V_{DD} = 3.3 V$,	V _O = 1.65 V		33		mA
		$V_{DD} = 3.6 V$,	V _O = 0.4 V			14	

[†] All typical values are at respective nominal V_{DD}.



[‡] For IDD over frequency see Figure 7.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
t(lock)	PLL lock time	f = 100 MHz			10		μs
	Phase offset (CLKIN to FBIN)	f = 8 MHz to 66 MHz, Vth = V _{DD} /2 (see Note 5)		-200		200	
^t (phoffset)		$f = 66 \text{ MHz to } 20 \text{ Vth} = V_{DD}/2 (see$,	-150		150	ps
^t PLH	Low-to-high level output propagation delay	S2 = High,	S1 = Low (PLL bypass)	2.5		6	ns
^t PHL	High-to-low level output propagation delay	f = 1 MHz,	$C_L = 25 pF$				
t _{sk(o)}	Output skew (Yn to Yn) (see Note 4)					150	ps
	Part-to-part skew	S2 = high,	S1 = high (PLL mode)			600	ps
^t sk(pp)		S2 = high,	S1 = low (PLL bypass)			700	
		f = 66 MHz to 200 MHz, C _L = 15 pF				±100	
^t jit(cc)	Jitter (cycle-to-cycle)		0 MHz, C _L = 25 pF MHz (see Figure 6)			±150	ps
odc	Output duty cycle	f = 8 MHz to 200	MHz	43%		57%	
t _{sk(p)}	Pulse skew	S2 = High, f = 1 MHz,	S1 = low (PLL bypass) C _L = 25 pF			0.7	ns
		C _L = 15 pF,	See Figure 4	0.8		3.3	
t _r	Rise time rate	C _L = 25 pF,	See Figure 4	0.5		2	V/ns
		C _L = 15 pF,	See Figure 4	0.8		3.3	.,,
t _f	Fall time rate	$C_L = 25 pF$,	See Figure 4	0.5		2	V/ns

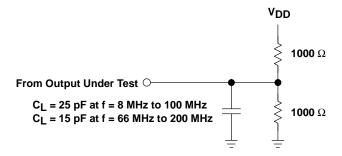


[†] All typical values are at respective nominal V_{DD}.

NOTES: 4. The t_{sk(0)} specification is only valid for equal loading of all outputs.

5. Similar waveform at CLKIN and FBIN are required. For phase displacement between CLKIN and Y-outputs see Figure 5.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: $Z_Q = 50 \Omega$, $t_f < 1.2 \text{ ns}$, $t_f < 1.2 \text{ ns}$.
- C. The outputs are measured one at a time with one transition per measurement.

Figure 1. Test Load Circuit

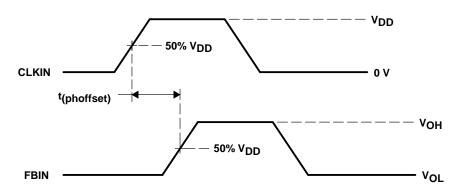
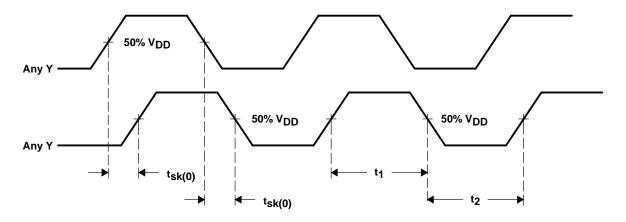


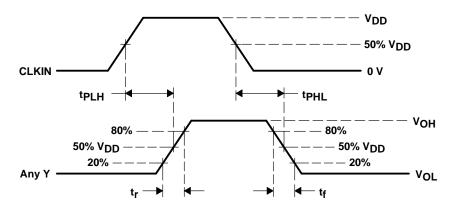
Figure 2. Voltage Thresholds for Measurements, Phase Offset (PLL Mode)



NOTE: odc = $t_1/(t_1 + t_2) \times 100\%$

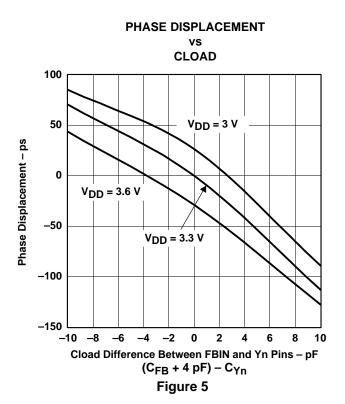
Figure 3. Output Skew and Output Duty Cycle (PLL Mode)

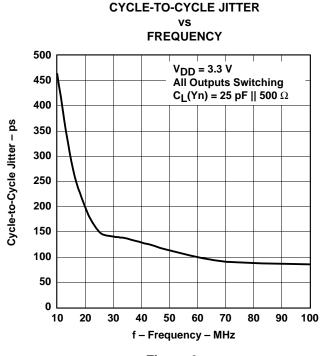
PARAMETER MEASUREMENT INFORMATION



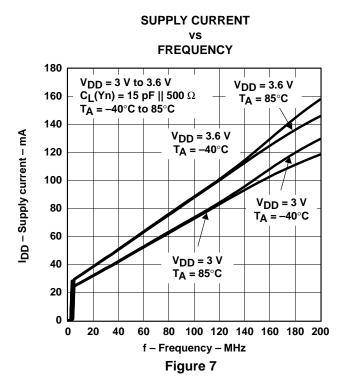
NOTE: $t_{Sk(p)}=|t_{PLH}-t_{PHL}|$

Figure 4. Propagation Delay and Pulse Skew (Non-PLL Mode)





PARAMETER MEASUREMENT INFORMATION

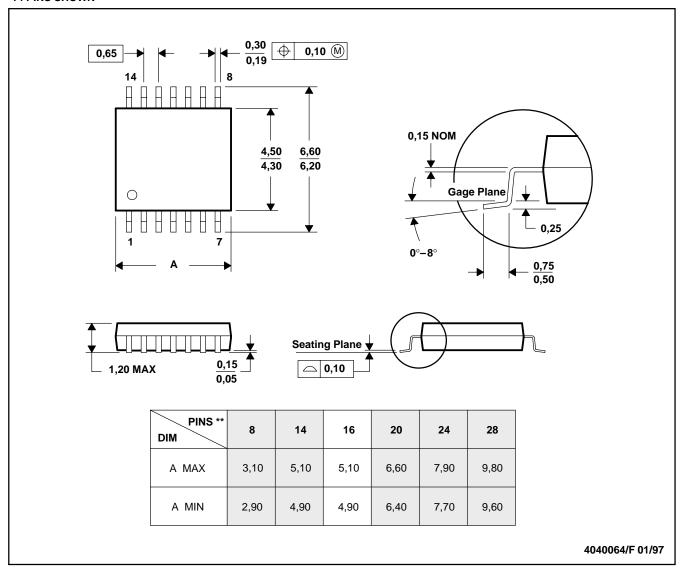


MECHANICAL DATA

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

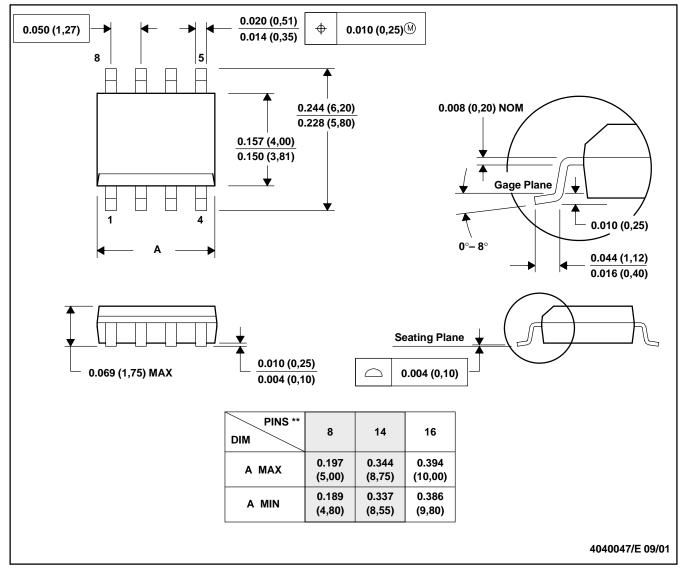
D. Falls within JEDEC MO-153

MECHANICAL DATA

D (R-PDSO-G**)

8 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

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